

## **Product Change Notification**

PCN No.	PCN_E	EC25_Series_20180713_I	EN	Date of Issue (DD/MM/YYYY)	13/07/2018
1. General Information					
Types of Change		Manufacturing Process Optimization			
Description of Changes		Added thermal adhesives between the shielding cover and PCBA of EC25 series module.			
Reasons of Change		In order to achieve a better thermal dissipation performance of EC25 series module, the thermally conductive adhesives will be added between the shielding cover and PCBA.			
2. Information for Affected Products					
Affected Products Information					
Model			Ordering Code		
EC25-E/EC25-E Mini PCIe			No change		
EC25-A/EC25-A MINIPCIE			No change		
EC25-V/EC2		5-V MINIPCIE		No change	
EC25-J/EC2		5-J MINIPCIE	No change		
EC25-AU/EC25-AU MINIPCIE			No change		
EC25-/		i-AUT		No change	
EC25-AUTL			No change		
Affected Products Release Time:  Samples for Affected Products will be available from					
3. Impacts of the Change					
Risk Assessmer	nt	<ol> <li>The adoption of thermally conductive adhesives is only an enhancement of the thermal dissipation performance, no risk will be added.</li> <li>The ordering codes remain unchanged.</li> </ol>			
Suggested with thermal conductive adhesives can fully meet the qualification and performant requirements, and a better thermal dissipation performance will be achieved					on and performance

Email: info@quectel.com



Therefore, the adoption of thermally conductive adhesives is highly recommended by Quectel.

## 4. Customer Acknowledgement of Receipt

Please acknowledge receipt of this change notification by replying to info\_PCN@quectel.com.

If no feedback is received within 30 days after the issue date of this notification, then Quectel may accept that this change has been tacitly accepted and can implement the change as indicated above.

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